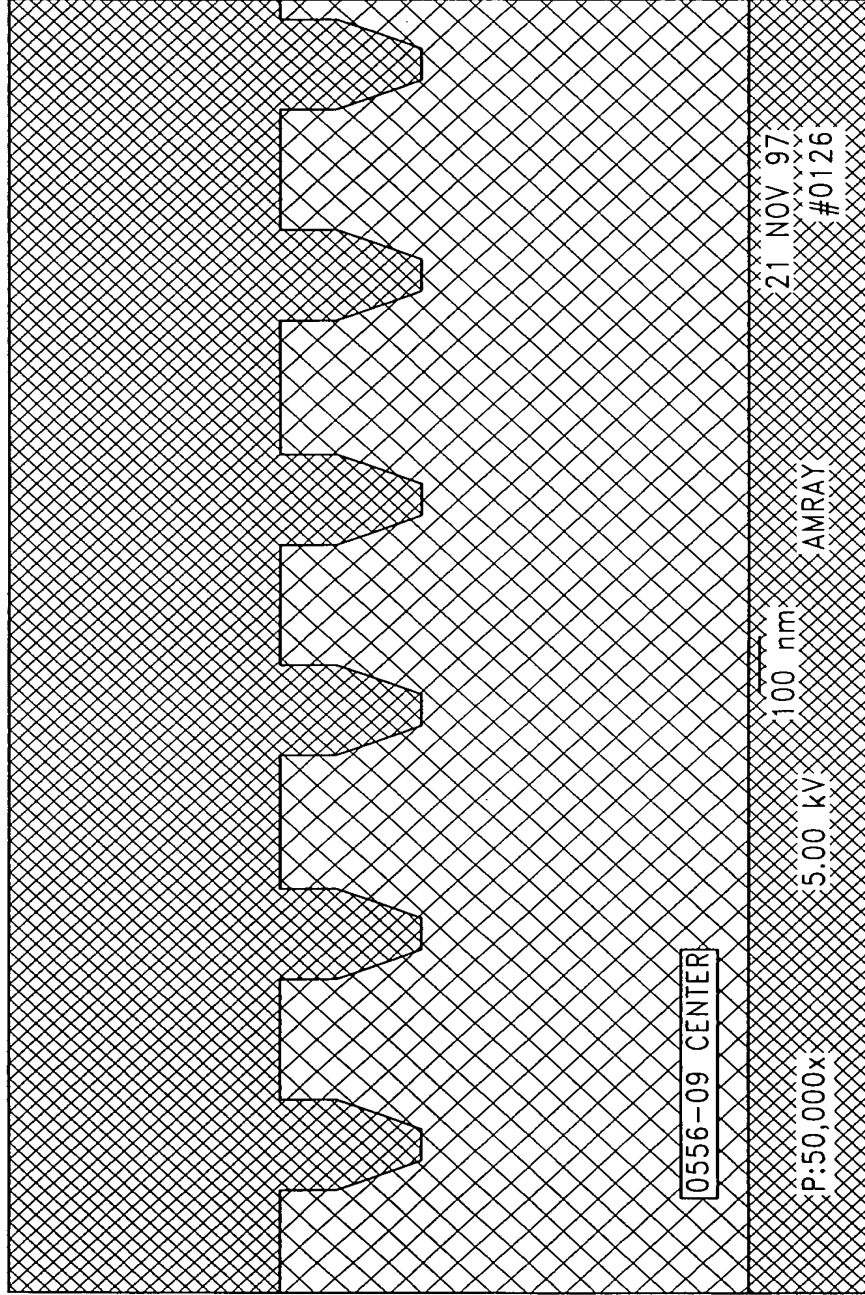
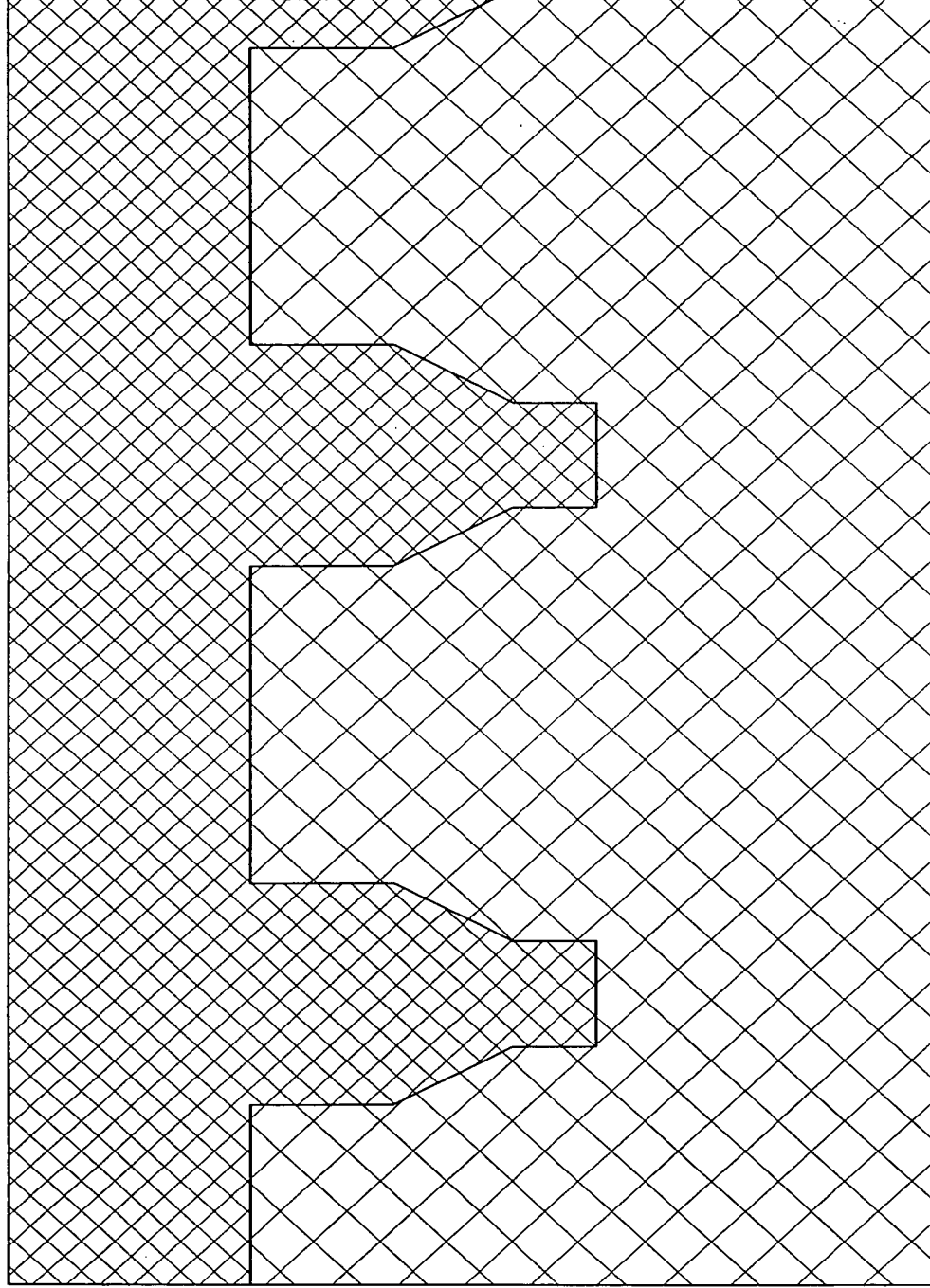


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**FIG. 1**  
(PRIOR ART)

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**FIG. 2**  
(PRIOR ART)

process: Flowfill +  $H_2SO_4$  dip + 1000°C anneal

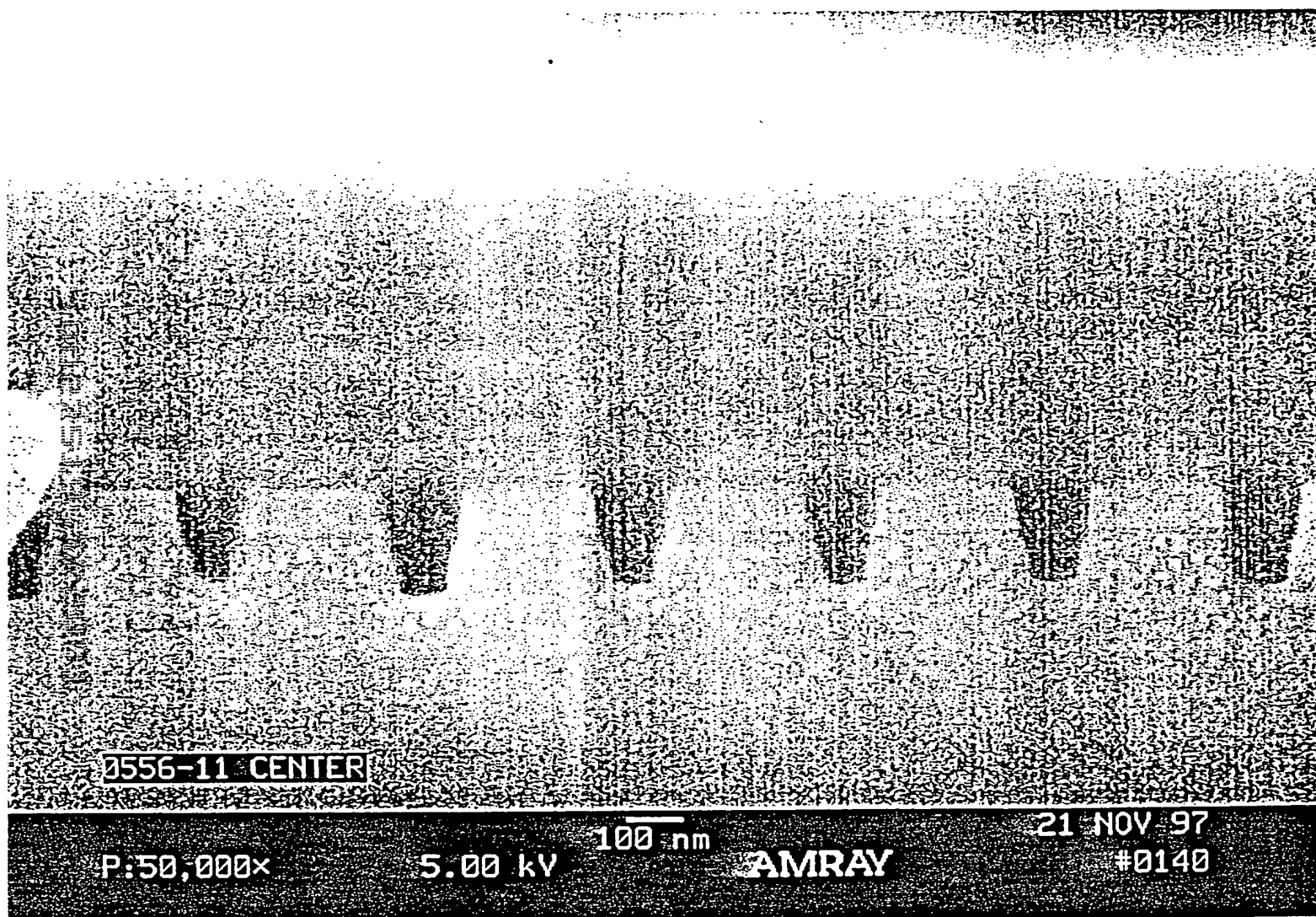


FIG. 3

process: Flowfill +  $H_2SO_4$  dip +  $1000^\circ C$  anneal

enlarged picture of wafer # 11

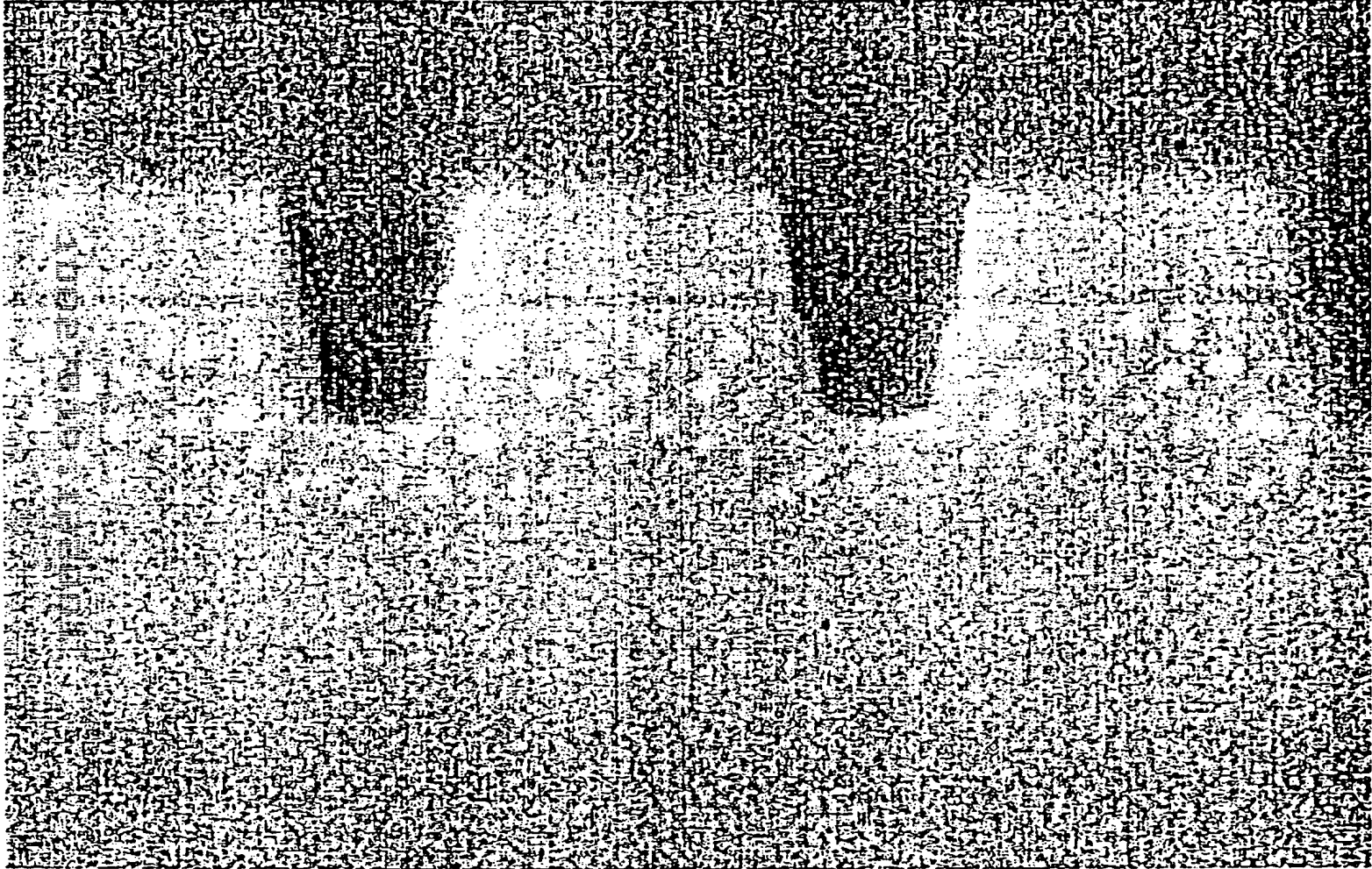
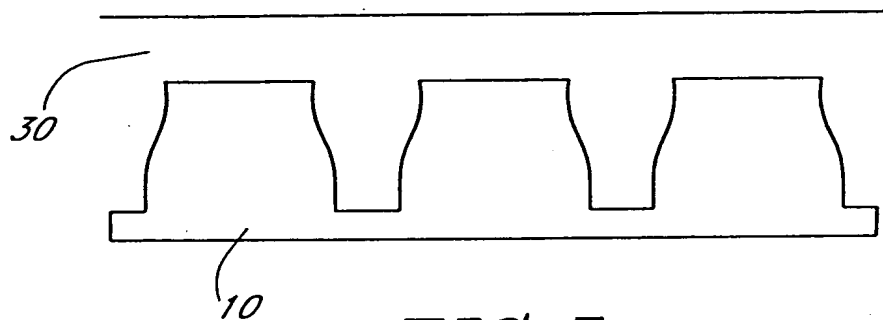
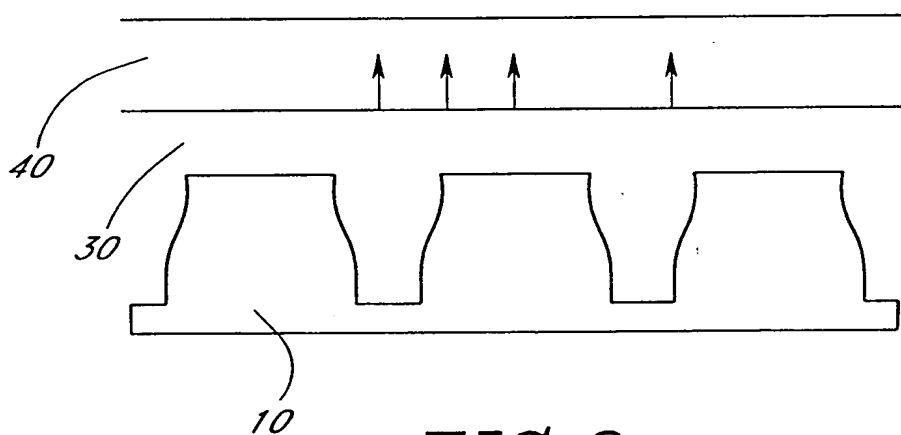


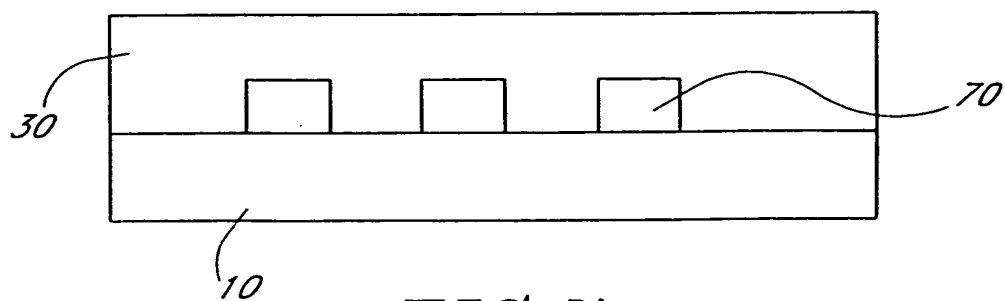
FIG. 4



**FIG. 5**

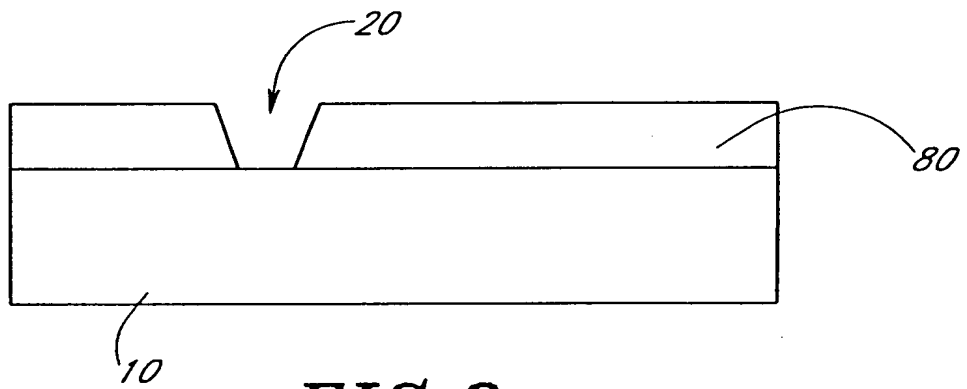


**FIG. 6**



**FIG. 7**

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**FIG. 8**